Prodn. of layered PCB with good workability and UV shielding - comprises placing surface layer of woven glass fibre impregnated with thermosetting resin in similar substrate contg. UV absorbing agent

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No Kind Date Applicat No Kind Date Week

JP 3214685 A 19910919 JP 908123 A 19900119 199144 B

Priority Applications (No Type Date): JP 908123 A 19900119

Abstract (Basic): JP 3214685 A

Layered board is produced by (1) placing a surface layer of glass fibre woven fabric impregnated with thermosetting resin on a substrate layer composed of glass fibre woven fabric impregnated with a resin composition contg 100 wt. pts of matrix thermosetting resin, 10-200 wt. pts of inorganic filler and 0.5-30 wt. pts of inorganic UV absorbing agent, and then (2) pressing the layers together under heating.

UV absorbing agent pref. has good absorption a wave length range of 300-500 nm, and is e.g. composed of Zn oxide or Ti oxide. The amount of the absorbing agent for the layered boards with thickness of 0.8 mm, 1.2 mm and 1.6 mm is pref. 4-10 wt.%. 3-8 wt % and 1-3 wt.% respectively under light exposure of 600 mJ/cm2.

USE/ADVANTAGE- The layered board shows excellent UV shielding property and workability in punching or drilling, and is suitable as material for printed circuit board.

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Title Terms: PRODUCE; LAYER; PCB; WORK; ULTRAVIOLET; SHIELD; COMPRISE; PLACE; SURFACE; LAYER; WOVEN; GLASS; FIBRE; IMPREGNATE; THERMOSETTING; RESIN; SIMILAR; SUBSTRATE; CONTAIN; ULTRAVIOLET; ABSORB; AGENT

Derwent Class: A85; L03; P73; V04

International Patent Class (Additional): B32B-015/08; C08J-005/24;
H05K-001/03

File Segment: CPI; EPI; EngPI

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